

1. (Amended) A fabricating method of a semiconductor package, comprising the steps of:
providing a substrate having a device-mounting region on a surface of the substrate, and a wire bonding region predefined around the device-mounting region for forming a plurality of bonding fingers thereon;
mounting a plurality of passive devices on the device-mounting region;
using an insulative material for encapsulating the passive devices;
disposing a semiconductor chip on a surface of the insulative material above the passive devices, such that the semiconductor chip is free of contact with the passive devices and the substrate;
providing a plurality of bonding wires for electrically connecting the semiconductor chip to the bonding fingers of the substrate;
forming an encapsulant for encapsulating the semiconductor chip and the bonding wires;
and
providing a plurality of conductive members for electrically connecting the substrate to an external device.

11. (Amended) A semiconductor package, comprising:
a substrate having a device-mounting region predefined on a surface of the substrate, and a wire bonding region predefined around the device-mounting region for forming a plurality of bonding fingers thereon;
a plurality of passive devices attached to the device-mounting region;
an insulative material for encapsulating the passive devices;
a semiconductor chip disposed on a surface of the insulative material above the passive devices, such that the semiconductor chip is free of contact with the passive devices and the substrate;
a plurality of bonding wires for electrically connecting the semiconductor chip to the bonding fingers of the substrate;
an encapsulant for encapsulating the semiconductor chip and the bonding wires; and
a plurality of conductive members for electrically connecting the substrate to an external device.